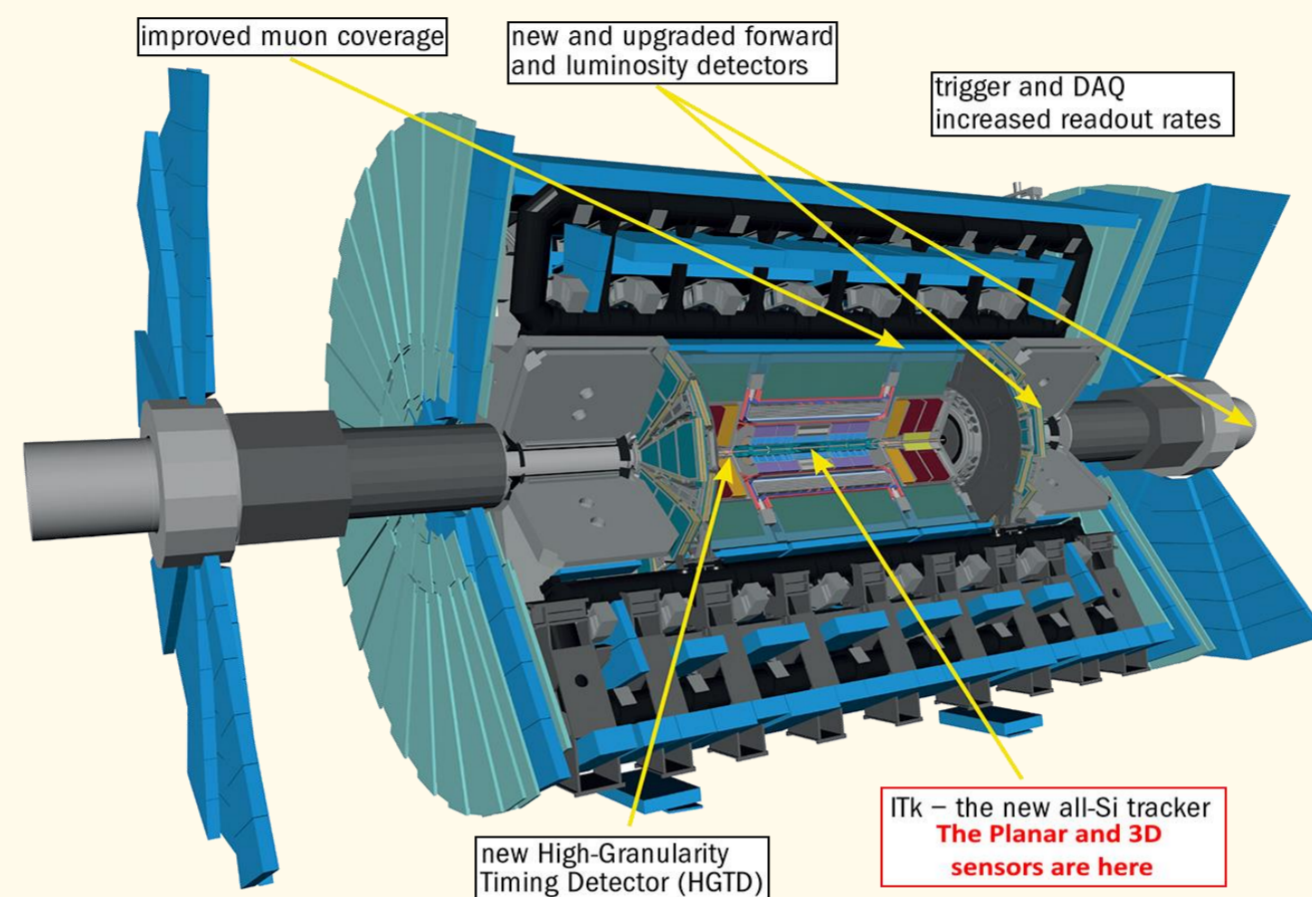
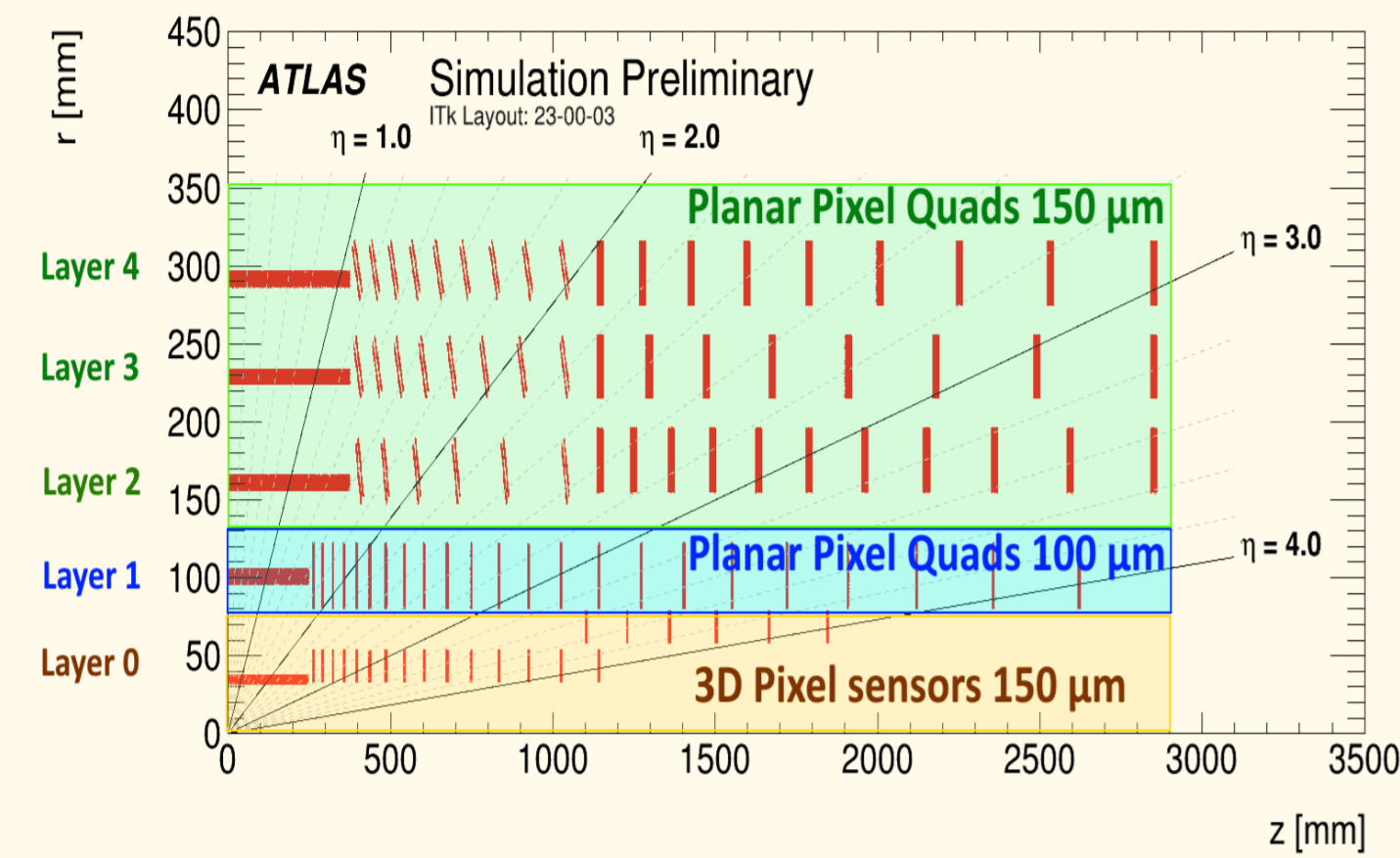




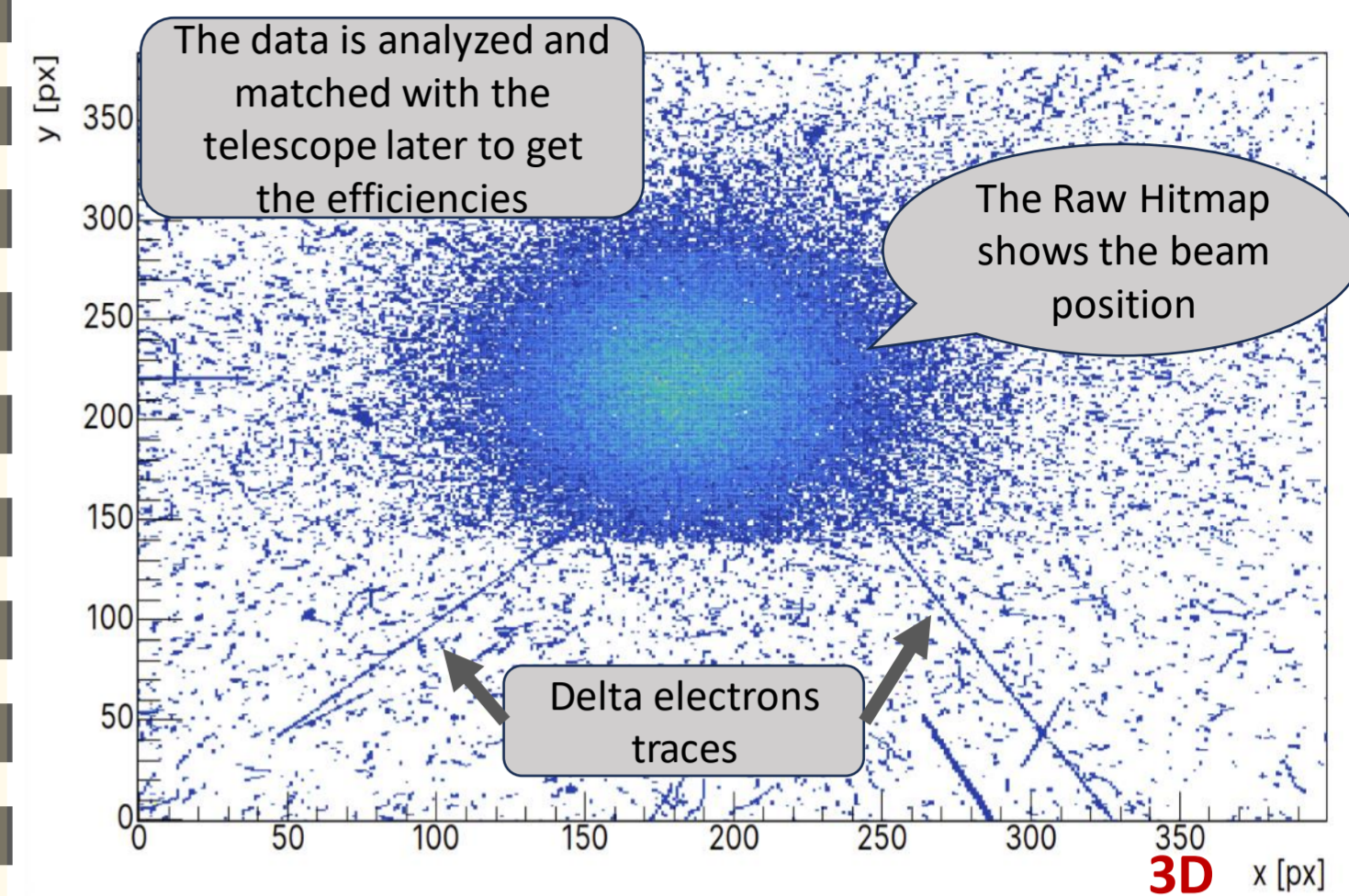
## Introduction

In the future the entire tracking detector of the ATLAS experiment must be replaced. The new Inner Tracker (ITk) must withstand extreme radiation conditions at the High Luminosity LHC (HL-LHC). The ITk will be equipped with sensors provided by MICRON (planar 100 & 150  $\mu\text{m}$  thick), SINTEF (3D 150  $\mu\text{m}$  thick with 50x50  $\mu\text{m}^2$  pixel cell),

HPK (planar 150  $\mu\text{m}$  thick) and FBK<sup>3</sup> (planar 100  $\mu\text{m}$  thick and 3D 150  $\mu\text{m}$  thick with 25x100  $\mu\text{m}^2$  and 50x50  $\mu\text{m}^2$  pixel cell). In this poster, we present efficiency results of SINTEF 3D<sup>2</sup> and HPK planar<sup>1</sup> sensors. Such sensors were tested at fluences above  $1.0 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$  (SINTEF 3D) and  $4.31 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$  (HPK planar).



## Hitmap



## Results

The plots below show the average pixel efficiency as a function of the bias voltage for some irradiated sensors.

- 3D SINTEF sensor was irradiated at  $1.0 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$
- Planar HPK sensor was irradiated at  $4.31 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

For both sensor types :

- We find an efficiency above specifications
- As expected, the inefficiency shown in the in-pixel hitmap for the 3D sensor perpendicular to the beam is not visible at an angle giving a higher average efficiency.

## 3D and Planar Pixel Sensors

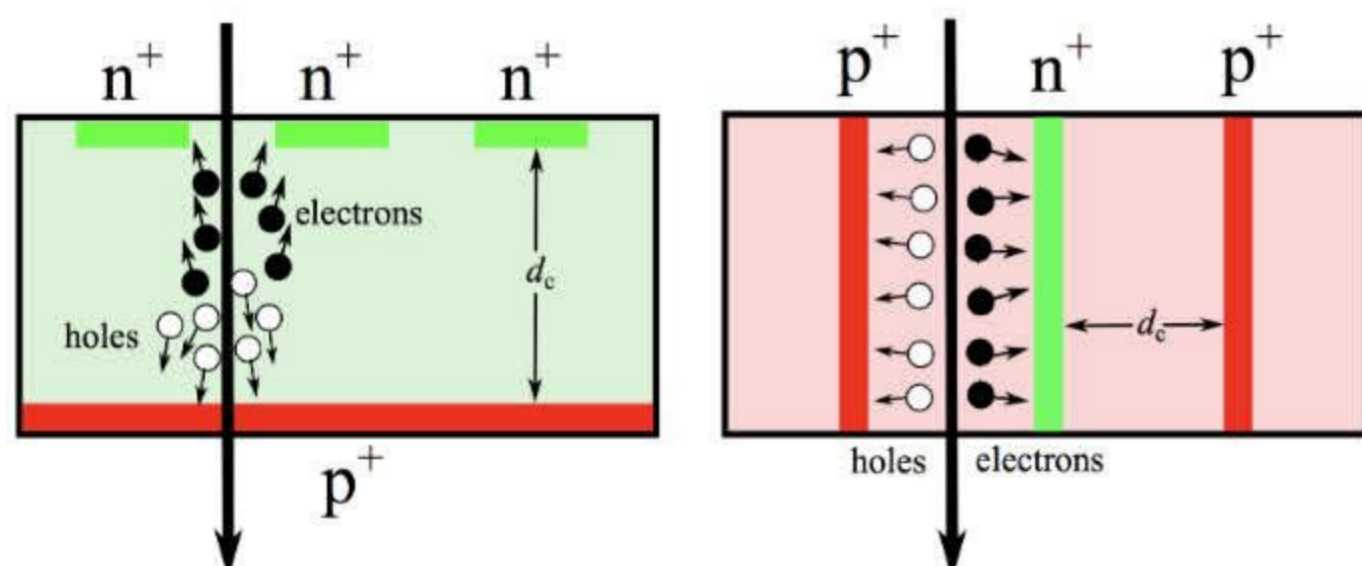
Both sensors are filled with n-type and p-type electrodes vertically or horizontally into the silicon bulk. When a charged particle goes through the active volume, charges move to the electrodes, and we can gather the signal on each pixel.

### PLANAR:

- Cheaper
- Collection of the charges depends on the thickness

### 3D:

- Fast charge collection
- Better radiation hardness



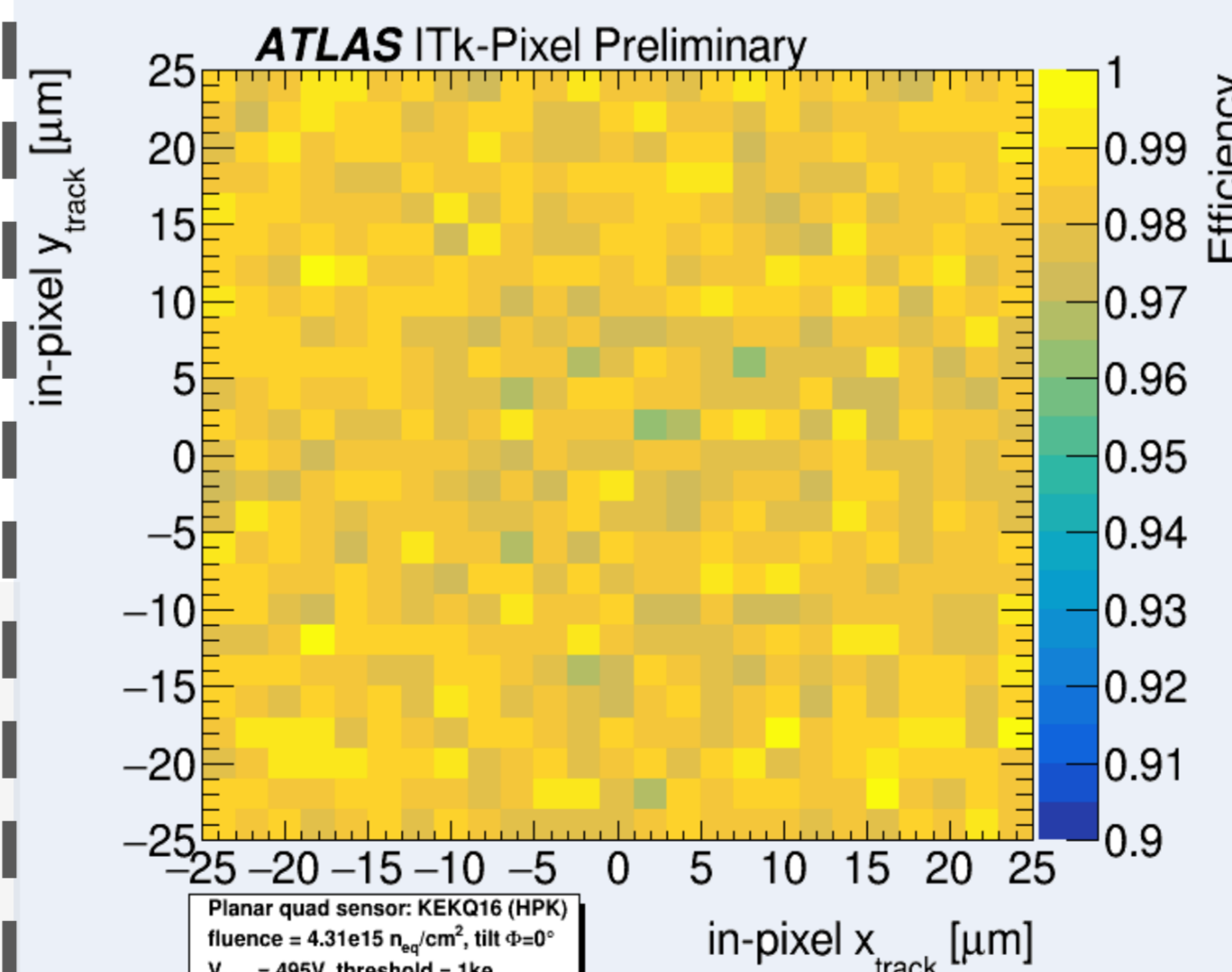
## In-Pixel Efficiency Maps

Telescope tracks crossing the detector under test (DUT) are matched with hits on the DUT. The efficiency is defined as the ratio between matched tracks and total tracks. The efficiency is then plotted as a function of the relative position in the pixel for all pixels

Overall efficiency is >96 % (required performance for perpendicular configuration). In-pixel efficiency map highlights the internal structure of each pixel:

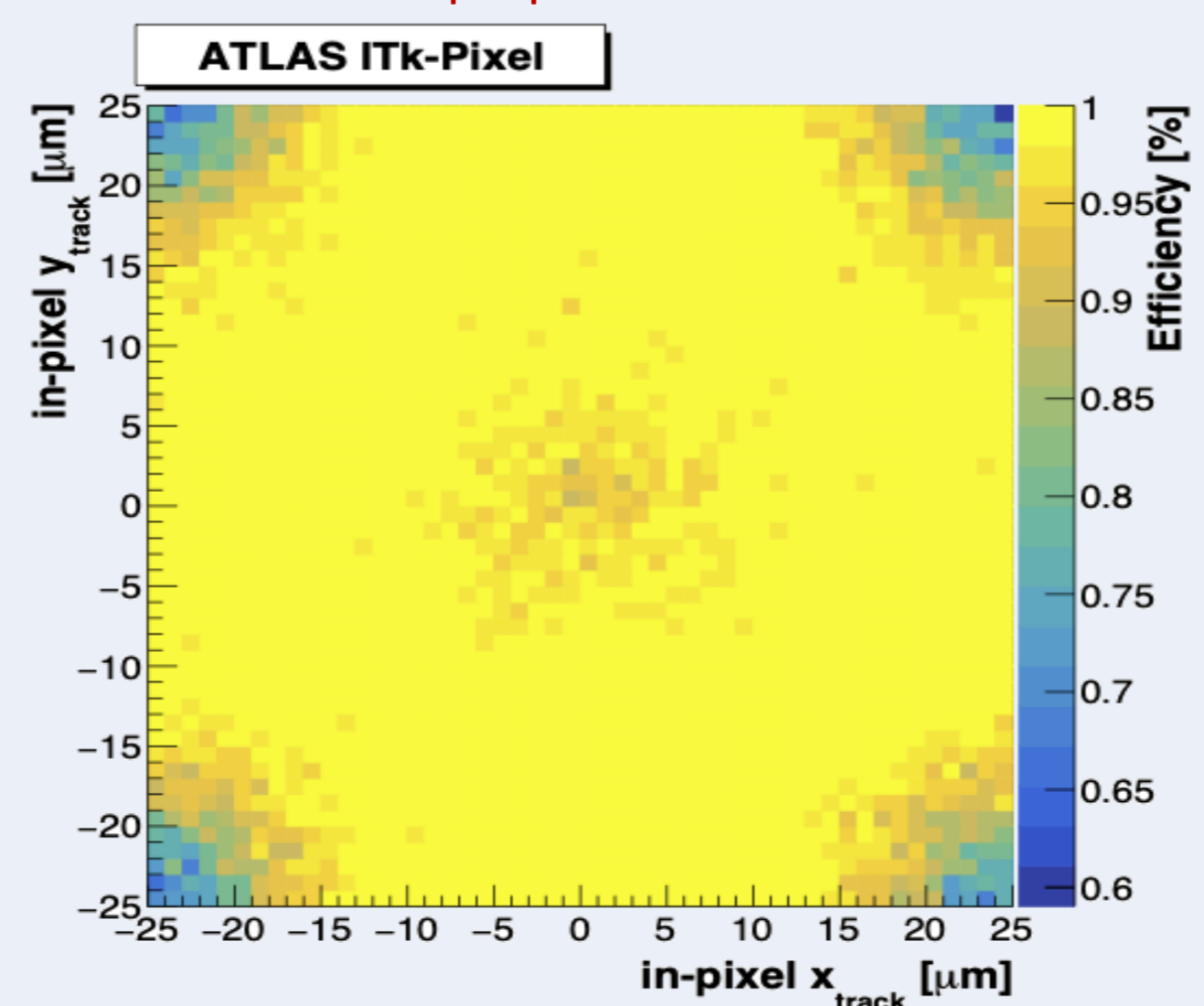
### Planar<sup>1</sup>

- In the planar sensor at ~500 V no structure is visible even after irradiations.

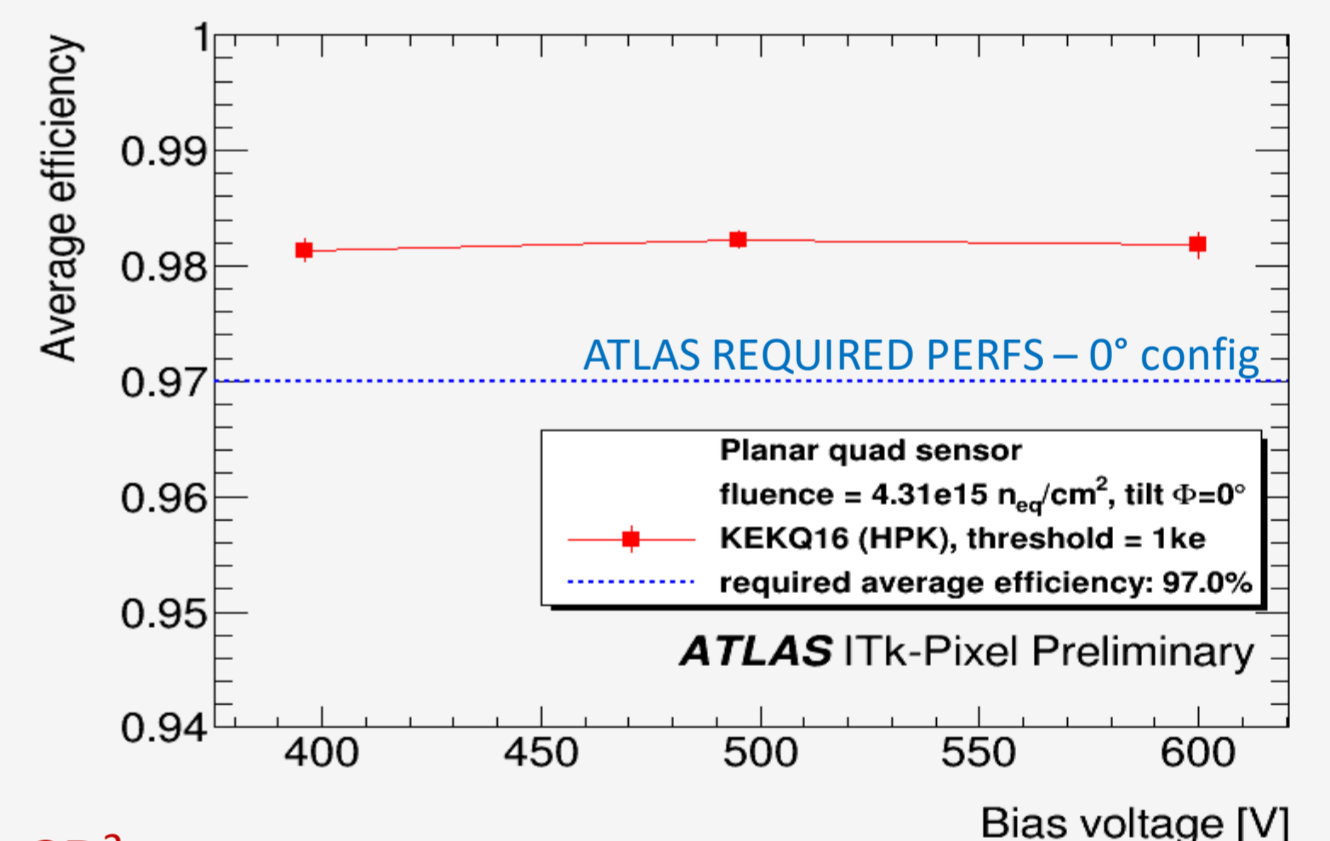


### 3D<sup>2</sup>

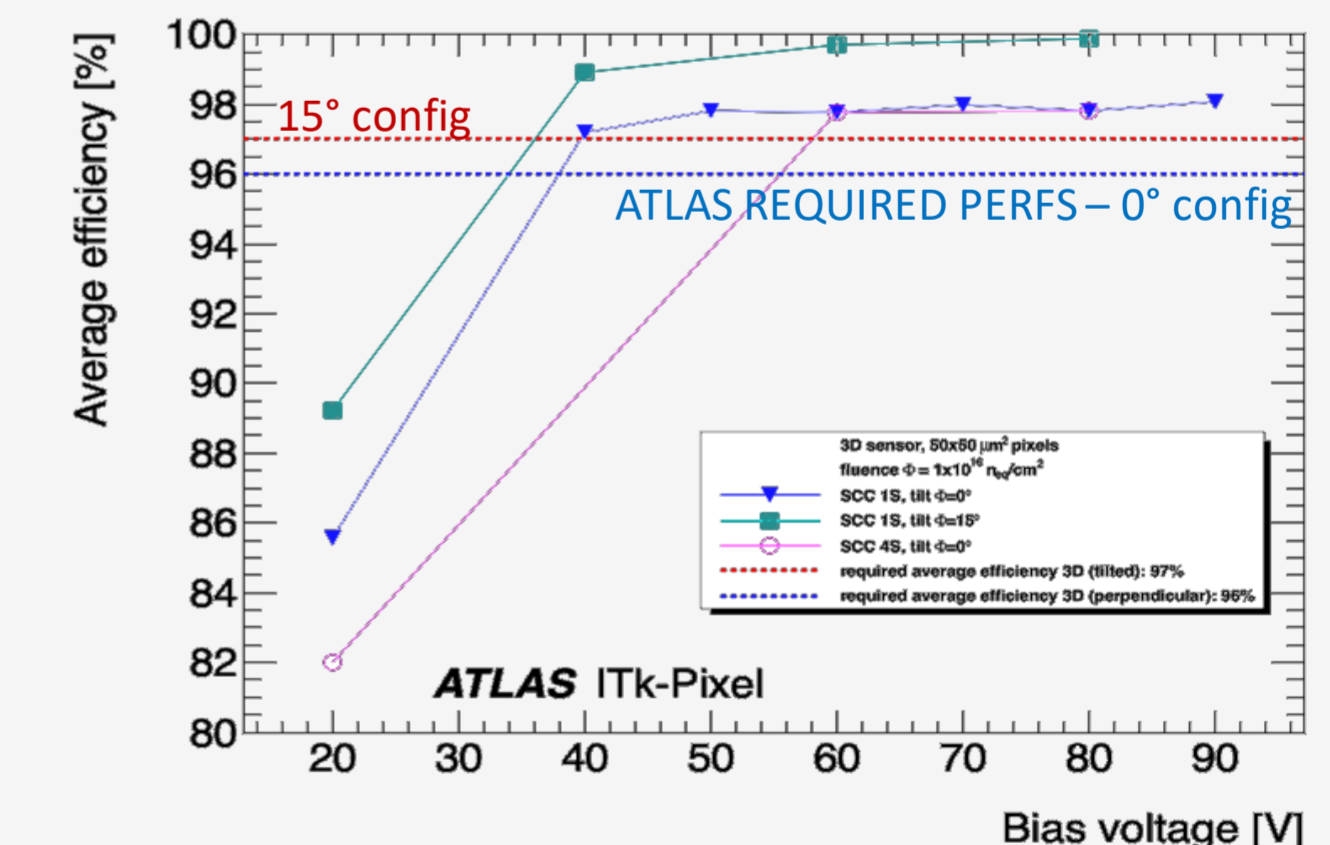
- In the 3D sensor at 60 V the inefficiency due to p+ columns is visible, this is expected for a DUT mounted perpendicular to the beam.



### Planar<sup>1</sup>



### 3D<sup>2</sup>

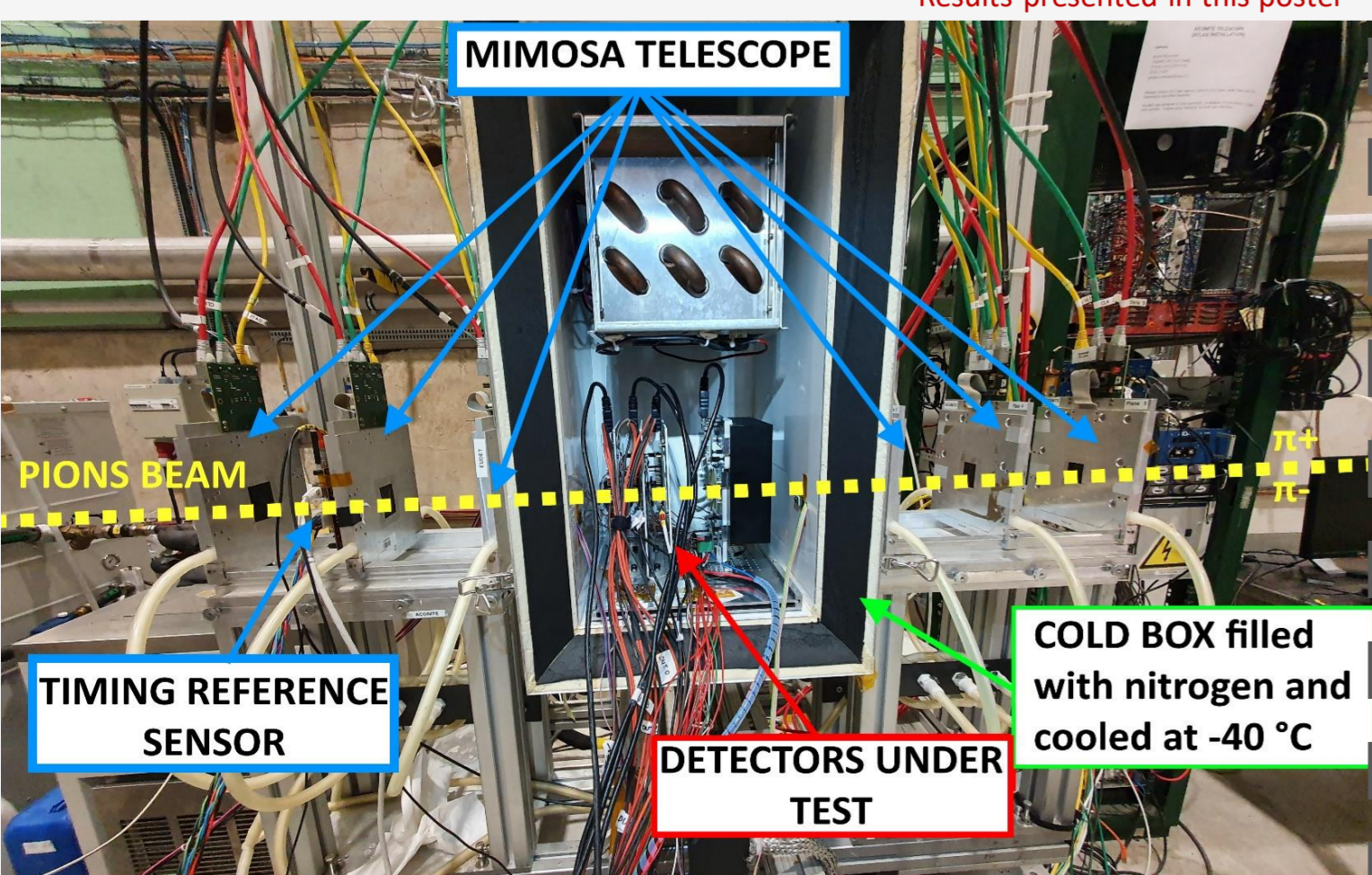


## Test Beam Setup

The EUDET Pixel Telescope

- At the CERN SPS North Area H6 test beam line
- Tracking capabilities of 6 MIMOSA26 (MAPS) planes for track reconstruction
- Beam of 120 GeV pions ( $\pi^+$  and  $\pi^-$ )
- Tested sensors: planar 100  $\mu\text{m}$  by FBK, planar 150  $\mu\text{m}$  by HPK\*, 150  $\mu\text{m}$  3D by SINTEF (50x50  $\mu\text{m}^2$ )\* and FBK (50x50 and 25x100  $\mu\text{m}^2$ ).

\*Results presented in this poster



## Conclusion

We present an efficiency analysis and sensors from Run 6. The sensors meet ATLAS ITk specifications:

- ☐ SINTEF 3D<sup>2</sup> :
  - >97 % efficiency in 0° perpendicular configuration ✓
  - >98 % efficiency at 15° tilted configuration ✓
- ☐ HPK Planar quad<sup>1</sup>
  - >98 % efficiency in 0° perpendicular configuration ✓
- ☐ FBK 3D<sup>3</sup> sensors also above >96 % (not shown here)